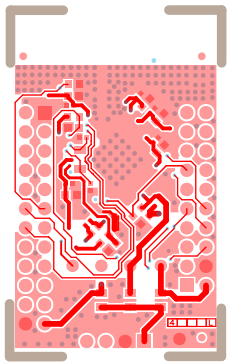
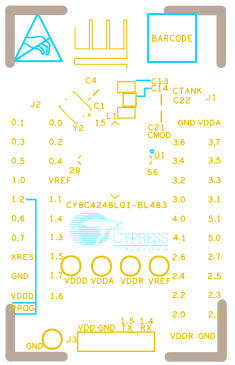


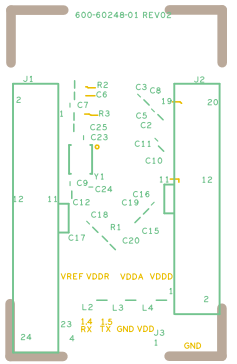
600-60248-01 REV02 PRIMARY SIDE



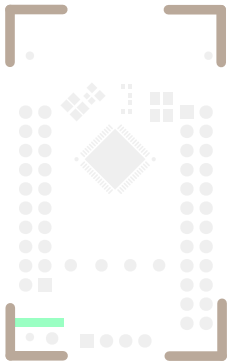
600-60248-01 REV02 SECONDARY SIDE



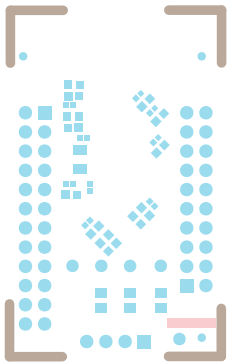
600-60248-01 REV02 PRIMARY SILKSCREEN



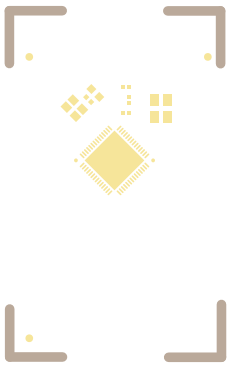
600-60248-01 REV02 SECONDARY SILKSCREEN



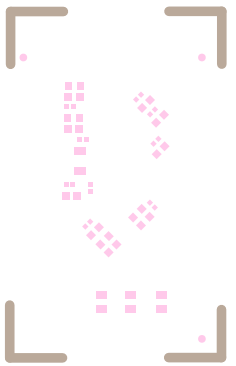
600-60248-01 REV02 PRIMARY SOLDERMASK



600-60248-01 REV02 SECONDARY SIDE

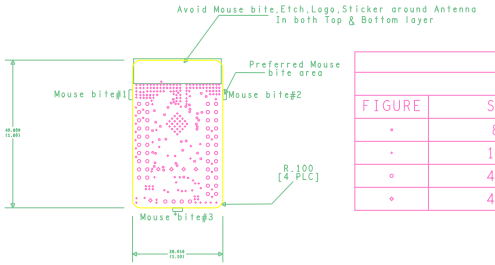


600-60248-01 REV02 PRIMARY SOLDERPASTE



600-60248-01 REV02 SECONDARY SOLDERPASTE

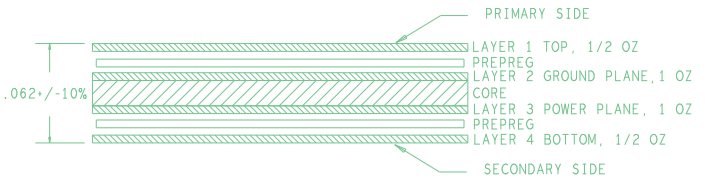
REVISIONS			
REV	DESCRIPTION	DATE	APPROVED
01	ALPHA RELEASE	03/02/15	RKPM
02	PRODUCTION RELEASE	04/01/15	RKPM



DRILL CHART: CY8CKIT-143				
ALL UNITS ARE IN MILS				
FIGURE	SIZE	TOLERANCE	PLATED	QTY
•	8.0	+3.0/-3.0	PLATED	38
•	10.0	+3.0/-3.0	PLATED	193
◦	40.0	+3.0/-3.0	PLATED	48
◦	43.0	+3.0/-3.0	PLATED	5

NOTES:(UNLESS OTHERWISE SPECIFIED)

1. RoHS COMPLIANT CERTIFICATION OR MATERIAL DECLARATION REQUIRED.
2. MATERIAL:
   A. IS410 OR EQUIVALENT. MATERIAL MUST CONFORM TO UL94V-0.
   B. USE HTE COPPER, AS SPECIFIED IN THE CROSS SECTION DIAGRAM.
   C. OVERALL METAL TO METAL THICKNESS AS SPECIFIED IN THE CROSS SECTION.
3. DRILLING:
   A. DIAMETERS IN DRILL TABLE ARE FINISHED HOLE SIZES +/-.003 tol.
      UNLESS OTHERWISE SPECIFIED IN DRILL TABLE.
   B. TEARDROP ALLOWED ON ENTRY OF VIA ON EVERY TRACE LAYER.
4. PLATING:
      COPPER PLATING IN THRU-HOLES .001 min.
5. MARKING:
   A. SILKSCREEN IN WHITE NON-CONDUCTIVE EPOXY INK ON PRIMARY SIDE OF THE
      BOARD OR BOTH SIDES IF APPLICABLE.
   B. FABRICATOR TO PLACE DATE CODE, LOGO AND RoHS COMPILANT SYMBOL IN SILKSCREEN ON SECONDARY SIDE.
6. FINAL FABRICATION:
   A. SOLDRMASK PRIMARY AND SECONDARY SIDE OF BOARD USING LIQUID PHOTOIMAGABLE
      MASK MATERIAL OVER BARE COPPER, PER IPC-SM-840. MASK ARTWORKS PROVIDED
      ARE 1:1. SOLDERMASK COLOR **RED*
7. FINISH:
   A. SHALL BE ELECTROLESS NIKEL / IMMERSION GOLD(ENIG).
   B. NICKEL THICKNESS: 100-200 MICROINCHES.
   C. GOLD THICKNESS: 3-10 MICROINCHES.
8. BOARDS SHALL BE PURCHASED FROM UL RECOGNIZED VENDORS ONLY.
   FLAMABILITY RATING (94-V0).
9. MANUFACTURE BOARD TO BE IN ACCORDANCE WITH PERFORMANCE STANDARD
   IPC-6011/6012 CLASS 2 BOARD TO BE INSPECTED PER IPC-600-A CLASS 2.
10. MAXIMUM WRAP OR TWIST SHALL NOT EXCEED .007 in/in.
11. TESTING:
   A. FABRICATOR TO ADD TEST STRUCTURES OR CUPONS AS NEEDED.
   B. T-LINE IMPEDENCE TO BE TESTED OR GUARANTEE WITHIN 10% IF SPECIFIED IN
      THE CROSS SECTION. TOLERANCE TO BE +/-10% UNLESS OTHERWISE SPECIFIED.



UNLESS OTHERWISE SPECIFIED
DIMENSIONS ARE IN INCHES
TOLERANCES ON: ANGLES +/- 2°
2 PL DECIMALS +/- .010
3 PL DECIMALS +/- .005
THIRD ANGLE PROJECTIONS

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SIGNATURES		DATE
DRAWN	PRAO	04/01/15
CHECKED	RKPM	04/01/15
ENGRG	RKPM	04/01/15
ISSUED		

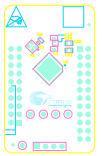
CYPRESS SEMICONDUCTOR
198 CHAMPION COURT
SAN JOSE, CA 95134
(408) 943-2600

FABRICATION DRAWING
CY8CKIT-143 PSoC 4 BLE 256K MODULE

SIZE	FSCM NO	DWG NO	REV
C		610-60240-01	02

SCALE: 1/1 SHEET: 1 OF 1

REVISIONS			
REV	DESCRIPTION	DATE	APPROVED
01	ALPHA RELEASE	03/02/15	RKPM
02	PRODUCTION RELEASE	04/01/15	RKPM



PRIMARY SIDE

600-60248-01 REV02 PRIMARY SILKSCREEN

UNLESS OTHERWISE SPECIFIED
DIMENSIONS ARE IN INCHES
TOLERANCES ON: ANGLES +/- 2°
2 PL DECIMALS +/- .010
3 PL DECIMALS +/- .005
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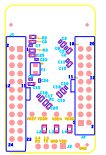
SAN JOSE, CA 95134
(408) 943-2600

ASSEMBLY DRAWING
CY8CKIT-143 PSoC 4 BLE 256K MODULE

SIZE	FSCM NO	DWG NO	REV
C		620-60248-01	02

SCALE: 1/1 SHEET: 1 OF 2



SECONDARY SIDE

600-60248-01 REV02 SECONDARY SILKSCREEN

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198 CHAMPION COURT
SAN JOSE, CA 95134
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ASSEMBLY DRAWING
CY8CKIT-143 PSoC 4 BLE 256K MODULE

SIZE	FSCM NO	DWG NO	REV
C		620-60248-01	02

SCALE: 1/1 SHEET: 2 OF 2

600-60248-01 REV02 GND LAYER

600-60248-01 REV02 VCC LAYER